

# FGA50N100BNTD 1000 V NPT Trench IGBT

### **General Description**

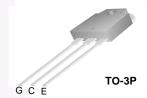
Using Fairchild's proprietary trench design and advanced NPT technology, the 1000V NPT IGBT offers superior conduction and switching performances, high avalanche ruggedness and easy parallel operation. This device offers the optimum performance for hard switching application such as UPS, welder applications.

#### **Features**

- High Speed Switching
- Low Saturation Voltage :  $V_{CE(sat)} = 2.5 \text{ V} @ I_C = 60 \text{ A}$
- High Input Impedance
- · Built-in Fast Recovery Diode

### **Application**

UPS, Welder, Induction Heating, Microwave Oven





### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Description		Ratings	Unit	
V <sub>CES</sub>	Collector-Emitter Voltage		1000	V	
V <sub>GES</sub>	Gate-Emitter Voltage		± 25	V	
	Collector Current	@ $T_C = 25^{\circ}C$	50	А	
I <sub>C</sub>	Collector Current	@ T <sub>C</sub> = 100°C	35	A	
I <sub>CM (1)</sub>	Pulsed Collector Current		100	A	
1	Diode Continuous Forward Current	@ T <sub>C</sub> = 25°C	30	A	
IF	Diode Continuous Forward Current	@ T <sub>C</sub> = 100°C	15	Α	
P <sub>D</sub>	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	156	W	
	Maximum Power Dissipation	@ T <sub>C</sub> = 100°C	63	W	
$T_J$	Operating Junction Temperature	-	-55 to +150	°C	
T <sub>stg</sub>	Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C	

(1) Repetitive rating : Pulse width limited by max. junction temperature

### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		0.8	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		25	°C/W

# **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FGA50N100BNTDTU	FGA50N100BNTD	TO-3P	Rail / Tube	N/A	N/A	30

## Electrical Characteristics of IGBT T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Chai	racteristics					
BV <sub>CES</sub>	Collector Emitter Breakdown Voltage	$V_{GE} = 0 \text{ V}, I_{C} = 1 \text{ mA}$	1000			V
I <sub>CES</sub>	Collector Cut-Off Current	V <sub>CE</sub> = 1000 V, V <sub>GE</sub> = 0 V			1.0	mA
I <sub>GES</sub>	G-E Leakage Current	$V_{GE} = \pm 25 \text{ V}, V_{CE} = 0 \text{ V}$			± 500	nA
On Char	racteristics					
V <sub>GE(th)</sub>	G-E Threshold Voltage	$I_C = 60 \text{ mA}, V_{CE} = V_{GE}$	4.0	5.0	7.0	V
	Collector to Emitter	I <sub>C</sub> = 10 A, V <sub>GE</sub> = 15 V		1.5	1.8	V
$V_{CE(sat)}$	Saturation Voltage	$I_C = 60 \text{ A},  V_{GE} = 15 \text{ V}$		2.5	2.9	V
C <sub>ies</sub>	C Characteristics Input Capacitance	V10 V V = 0 V		6000		pF
C <sub>oes</sub>	Output Capacitance	$V_{CE} = 10 \text{ V}, V_{GE} = 0 \text{ V},$		260		pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1 MHz		200		pF
	ng Characteristics					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{CC} = 600 \text{ V}, I_{C} = 60 \text{ A},$		140		ns
t <sub>r</sub>	Rise Time	$V_{CC} = 600 \text{ V}, I_C = 60 \text{ A},$ $R_G = 51 \Omega, V_{GE} = 15 \text{ V},$		320		ns
t <sub>d(off)</sub>	Turn-Off Delay Time	Resistive Load, $T_C = 25^{\circ}C$	/	630		ns
t <sub>f</sub>	Fall Time	1.100.0010 2000, 16 = 20 0		130	250	ns
$Q_g$	Total Gate Charge	V - 600 V I - 60 A		275	350	nC
Q <sub>ge</sub>	Gate-Emitter Charge	$V_{CE} = 600 \text{ V}, I_{C} = 60 \text{ A},$ $V_{GF} = 15 \text{ V}, T_{C} = 25^{\circ}\text{C}$		45		nC
Q <sub>gc</sub>	Gate-Collector Charge	VGE - 13 V,, 1C = 23 C		95		nC

# Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V	Diode Forward Voltage	I <sub>F</sub> = 15 A		1.2	1.7	V
$V_{FM}$	Didde Forward Voltage	I <sub>F</sub> = 60 A		1.8	2.1	V
t <sub>rr</sub>	Diode Reverse Recovery Time	$I_F = 60 \text{ A di}_F/\text{dt} = 20 \text{ A/us}$		1.2	1.5	us
IR	Instantaneous Reverse Current	VRRM = 1000 V		0.05	2	uA

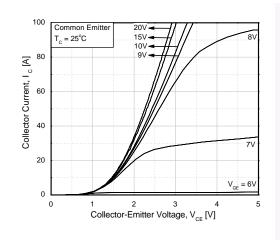


Fig 1. Typical Output Characteristics

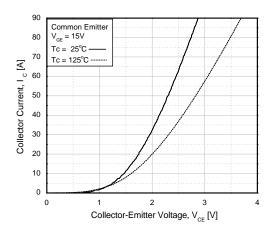


Fig 2. Typical Saturation Voltage Characteristics

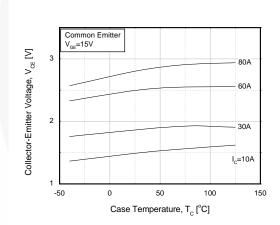


Fig 3. Saturation Voltage vs. Case
Temperature at Varient Current Level

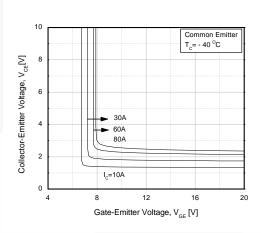


Fig 4. Saturation Voltage vs. V<sub>GE</sub>

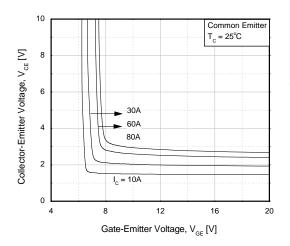


Fig 5. Saturation Voltage vs. V<sub>GE</sub>

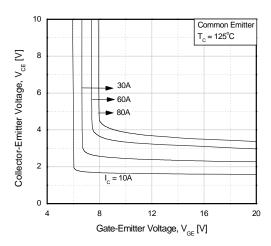
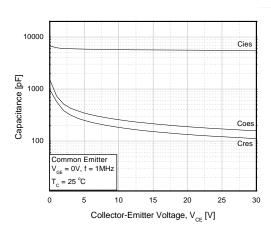


Fig 6. Saturation Voltage vs.  $V_{\text{GE}}$ 



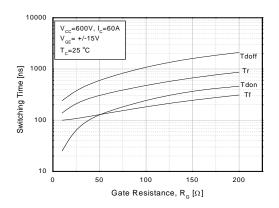
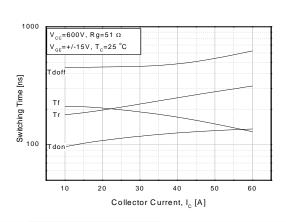


Fig 7. Capacitance Characteristics

Fig 8. Switching Characteristics vs.

Gate Resistance



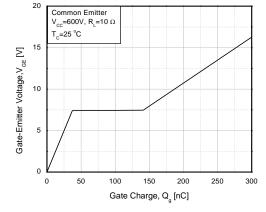
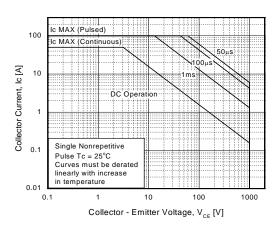


Fig 9. Switching Characteristics vs. Collector Current

Fig 10. Gate Charge Characteristics



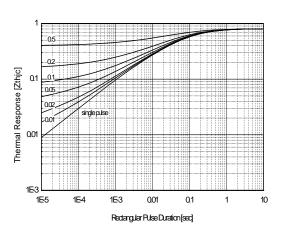
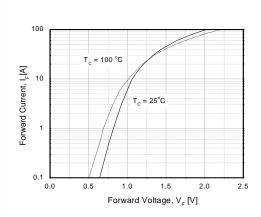


Fig 11. SOA Characteristics

Fig 12. Transient Thermal Impedance of IGBT



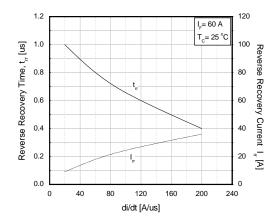
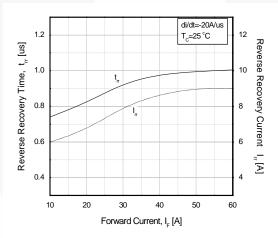


Fig 13. Forward Characteristics

Fig 14. Reverse Recovery Characteristics vs. di<sub>F</sub>/dt



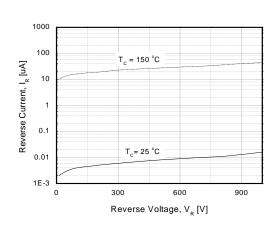


Fig 15. Reverse Recovery Characteristics vs. Forward Current

Fig 16. Reverse Current vs. Reverse Voltage

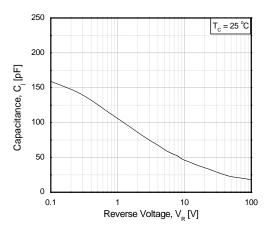


Fig 17. Junction capacitance

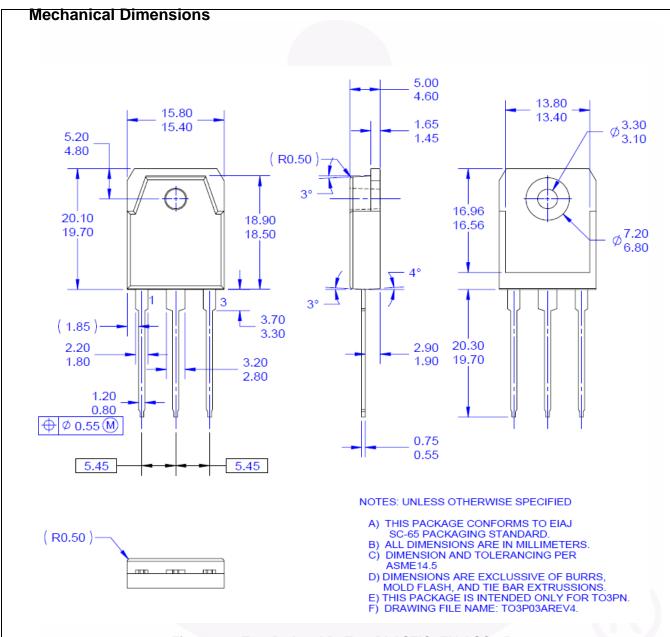


Figure 18. TO-3P 3L - 3LD, T03, PLASTIC, EIAJ SC-65

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